

**News Release**

**FOR IMMEDIATE RELEASE**

**BTU International to Highlight Advanced Reflow Solutions for Panel-Level Packaging and AI Server Manufacturing at SEMICON China 2026**

WESTFORD, Mass., March 24, 2026 — BTU International, Inc., a leading supplier of advanced thermal processing equipment for the electronics manufacturing market, will highlight its latest reflow technologies for panel-level packaging and AI server manufacturing at SEMICON China 2026, taking place March 25–27 at the Shanghai New International Expo Centre in Shanghai, China.



As semiconductor packaging and high-performance computing applications evolve, manufacturers are facing increasingly complex thermal processing challenges—from large-format panel-level packaging to high-mass AI server assemblies that require precise thermal control and consistent heat transfer.

BTU will showcase how its Aurora and Pyramax reflow platforms support these demanding applications through advanced convection control, strong thermal uniformity, and flexible system configurations. The systems are designed to support high-yield panel-level packaging with stable heat transfer, ultra-low oxygen processing below 30 ppm for improved solder wetting and micro-bump reliability, and controlled heating and cooling profiles that help minimize mechanical stress and panel warpage.

BTU will also highlight the Aurora 200N75 reflow oven for AI server assemblies, which are increasingly challenging due to high copper content, thick substrates, dense component

populations, and uneven thermal mass. The system delivers strong thermal uniformity across large, high-mass boards and offers configurations with up to 16 heating zones to optimize heating and cooling profiles for complex assemblies.

The system integrates BTU's Aqua Scrub flux management technology to reduce maintenance and maximize uptime, even when processing large server boards. BTU's system-level thermal architecture is designed to manage energy delivery across the entire oven, allowing manufacturers to run complex, high-mass boards while maintaining consistent soldering performance and stable process windows.

For more information about BTU International, visit [www.btu.com](http://www.btu.com).

### **About BTU International**

BTU International, a wholly-owned subsidiary of Amtech Group (Nasdaq: ASYS), is a global supplier and technology leader of advanced thermal processing equipment in the electronics manufacturing market. BTU's high-performance reflow ovens are used in the production of SMT printed circuit board assemblies and in semiconductor packaging processes. BTU also specializes in precision controlled, high-temperature belt furnaces for a wide range of custom applications, such as brazing, direct bond copper (DBC), diffusion, and sintering. BTU has operations in Westford, Massachusetts, and Shanghai, China, with direct sales and service in the U.S.A., Asia and Europe. Information about BTU International is available at [www.btu.com](http://www.btu.com).

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